



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Yutaka KANEDA et al.

Group Art Unit: 2826

Application No.: 09/909,827

Examiner: F. Erdem

Filed: July 23, 2001

Docket No.: 105128.0

For: FLEXIBLE PRINTED WIRING BOARDS

SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

As a supplement to the Request for Reconsideration filed on September 12, 2002,
please further amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 22 and 24 as follows:

B¹
22. (Amended) A flexible printed wiring board comprising a metal film, a resin coating on said metal film, and a metal bump located in an opening formed in said resin coating, the metal bump having a front face and connected at its bottom face to said metal film and having a height greater than the thickness of said resin coating, wherein said resin coating is completely removed from said front face of said metal bump to entirely expose the front face of said metal bump from the surface of said resin coating.

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24. (Amended) A flexible printed wiring board according to claim 23 wherein an electric device is mounted on said flexible printed wiring board and a bonding pad of said electric device is connected with the front face of said metal bump.

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